

AMENDMENTS TO THE CLAIMS

1 (Currently amended). An electronic component comprising an electronic component body ~~and having an external electrodes formed thereon, the external electrode comprising each including~~ a first sintered electrode layer and a second sintered electrode layer disposed thereon, the first and second sintered electrode layers ~~mainly containing~~ comprising different metals, wherein

the first sintered electrode layer ~~contains~~ comprises a first borosilicate glass containing an alkali metal, the first borosilicate glass containing 85% to 95% by weight of silicon and 0.5% to 1.5% by weight of the alkali metal based on 100% by weight of all contained elements other than boron according to analysis with a wavelength dispersive X-ray microanalyzer; and

the second sintered electrode layer ~~contains~~ comprises a second borosilicate glass containing an alkali metal, the second borosilicate glass containing 65% to 80% by weight of silicon and 3.5% to 8.0% by weight of the alkali metal based on 100% by weight of all contained elements other than boron according to analysis with a wavelength dispersive X-ray microanalyzer.

2 (Currently amended). The electronic component according to Claim 1, wherein the alkali metal contained in the first borosilicate glass ~~is~~ comprises potassium; and the alkali metal contained in the second borosilicate glass ~~is~~ comprises sodium.

3 (Currently amended). The electronic component according to Claim 1, wherein the metal ~~mainly contained~~ in the second sintered electrode layer ~~is~~ comprises a noble metal.

4 . The electronic component according to Claim 3, wherein the noble metal ~~is silver-palladium~~ comprises silver.

5 (Currently amended). The electronic component according to Claim 1, wherein the electronic component body includes internal electrodes comprising a metal; and the metal ~~mainly contained in~~ of the first sintered electrode layer is a metal that is alloyed with the internal electrodes.

6 (Currently amended). The electronic component according to Claim 5, wherein the internal electrodes ~~mainly contain~~ comprise nickel; and the metal that is alloyed with the internal electrodes ~~is~~ comprises copper.

7 (Currently amended). The electronic component according to ~~any one of Claims Claim 1 to 6~~, wherein ~~the~~ an external electrode ~~electrodes~~ of the electronic component ~~are for connecting~~ is connected to ~~patterned electrodes~~ an electrode on a mounting substrate with a conductive adhesive ~~prepared by dispersing a metal filler in a resin~~.

8 (Currently amended). A method for producing an electronic component including an electronic component body ~~and~~ having thereon an external electrode, wherein the external electrode includes electrodes formed thereon, ~~each including a~~ first sintered electrode layer and a second sintered electrode layer disposed thereon, the first and second sintered electrode layers ~~mainly~~ containing different metals, the method comprising ~~the steps of~~:

forming the first sintered electrode layer by providing an ~~applying~~ to the electronic component body having thereon a first conductive paste containing a first metal, ~~as a main component~~, and a first borosilicate glass that contains an alkali metal

and has a first softening temperature; and sintering the first conductive paste at a first sintering temperature which is higher than the first softening temperature; and

forming the second sintered electrode layer by applying to the first sintered electrode layer a second conductive paste containing a second metal which is different from the first metal and a second borosilicate glass that contains an alkali metal and has a second softening temperature lower than the first softening temperature; and sintering the second conductive paste at a second sintering temperature lower than the first softening temperature and higher than the second softening temperature.

9 (Currently amended). The method for producing the electronic component according to Claim 8, wherein ~~the second metal is sintered at the second sintering temperature, which~~ is lower than the melting temperature of the second metal, ~~using the second borosilicate glass;~~ and the second sintering temperature is lower than the first softening temperature by at least 50°C.

10 (Currently amended). The method for producing the electronic component according to Claim 8, wherein ~~the first metal is sintered at the first sintering temperature, which~~ is lower than the melting temperature of the first metal, ~~using the first borosilicate glass; the second metal is sintered at the second sintering temperature, which~~ is lower than the melting temperature of the second metal, ~~using the second borosilicate glass;~~ and the ~~decrease in~~ difference between the second sintering temperature ~~relative to~~ and the melting temperature of the second metal is larger than the difference between ~~decrease in~~ the first sintering temperature ~~relative to~~ and the melting temperature of the first metal.

11 (Currently amended). The method for producing the electronic component according to Claim 8, wherein the alkali metal ~~contained~~ in the first borosilicate glass ~~is~~ comprises potassium; and the alkali metal ~~contained~~ in the second borosilicate glass ~~is~~ comprises sodium.

12 (Original). The method for producing the electronic component according to Claim 8, wherein the second metal is a noble metal.

13 (Currently amended). The method for producing the electronic component according to Claim 12, wherein the noble metal ~~is silver-palladium~~ comprises silver.

14 (Currently amended). The method for producing the electronic component according to Claim 8 ~~any one of Claims 7 to 13~~, wherein the electronic component body includes internal electrodes; and the first metal is a metal that is ~~alloyed~~ alloys with the internal electrodes.

15 (Currently amended). The method for producing the electronic component according to Claim 14, wherein the internal electrodes ~~mainly contain~~ comprises nickel; and the metal that is alloyed with the internal electrodes ~~is~~ comprises copper.

16 (New) The electronic component according to Claim 4, wherein the metal in the second sintered electrode layer comprises silver-palladium.

17 (New) The electronic component according to Claim 4, wherein the alkali metal contained in the first borosilicate glass comprises potassium; and the alkali metal contained in the second borosilicate glass comprises sodium.

18 (New) The electronic component according to Claim 6, wherein the metal in the second sintered electrode layer comprises silver; the alkali metal contained in the first borosilicate glass comprises potassium; and the alkali metal contained in the second borosilicate glass comprises sodium.

19 (New) The electronic component according to Claim 7, wherein the metal in the second sintered electrode layer comprises silver; the alkali metal contained in the first borosilicate glass comprises potassium; and the alkali metal contained in the second borosilicate glass comprises sodium.

20 (New) The method of producing the electronic component according to Claim 8, wherein the metal in the second sintered electrode layer comprises silver-palladium.